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ACTION

(54) Title: PROCESS FOR CREATING VIAS FOR CIRCUIT ASSEMBLIES

(57) Abstract: Provided is a process for creating vias for a circuit assembly including the steps of (a) applying a curable coating composition to a substrate, some or all of which is electrically conductive, to form an uncured coating thereon; (b) applying a resist over the uncured coating; (c) imaging the resist in predetermined locations; (d) developing the resist to expose predetermined areas of the uncured coating; (e) removing the exposed areas of the uncured coating; and (f) heating the coated substrate of step (e) to a temperature and for a time sufficient to cure the coating. Also disclosed is a process of fabricating a circuit assembly.

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